

## **Technical Data Sheet**

**MODEL NO: S3020UV4-400** 

## Features:

- Package in 8mm tape on 7″ diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

## Applications:

●UV Light

Dice material	Emitted color	Lens Color
InGaN	Purple	Water Clear

# Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

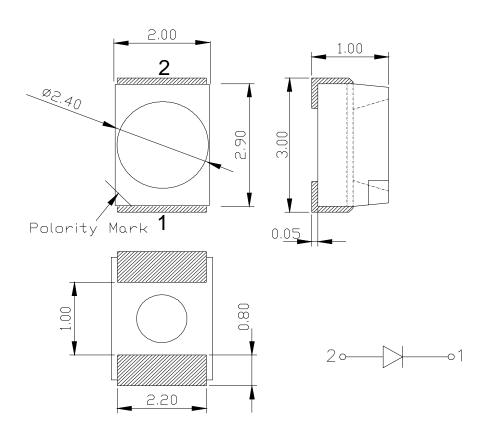
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	UIIIL
Dominant wavelength	IF=20mA	λD	395	400	405	nm
Forward voltage	IF=20mA	VF	3.0	3.2	3.4	V
Luminous intensity	IF=20mA	lv	20	30	40	mcd
Viewing angle at 50% lv	IF=10mA	2 <i>0</i> 1/2		120		Deg
Reverse current	V <sub>R</sub> =5V	lr		10		μΑ



## Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	100	mW
Forward current	lF	20	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-20 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 Duty Cycle,0.1ms Pulse Width)	lfP	100	mA

# PACKAGING DIMENSIONS (mm):



#### **Precautions For Use:**

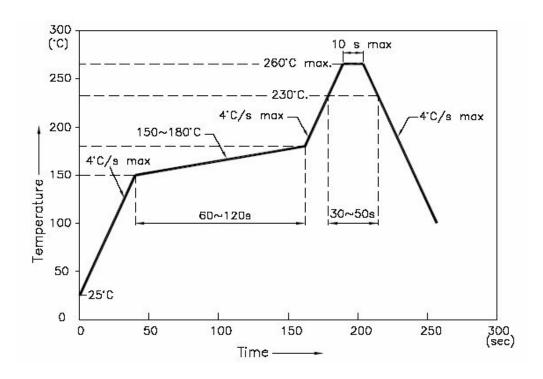
#### Over- current- proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

#### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.

### ■ Reflow Temp/Time



#### NOTES:

- 1. We recommend the reflow temperature  $245\,^{\circ}\mathrm{C}(\pm 5\,^{\circ}\mathrm{C})$ .the maximum soldering temperature should be limited to  $260\,^{\circ}\mathrm{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

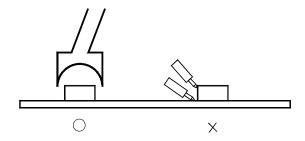


### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

#### **■**Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow , solder etc.